ROGERS CORPORATION

Advanced Circuit Materials

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Data Sheet
1.5000

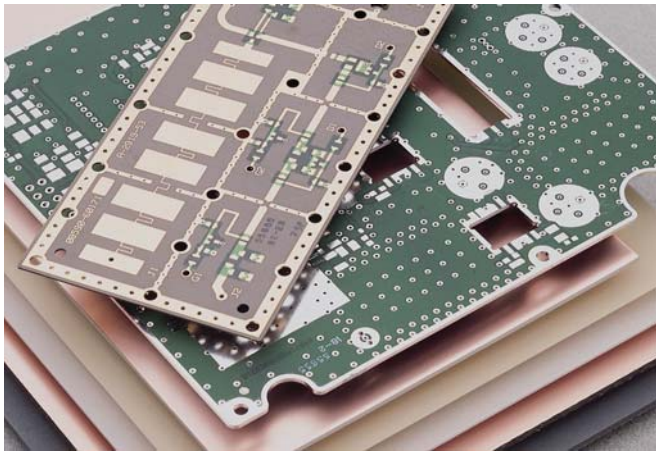
RT/duroid®5870 /5880 High Frequency Laminates

Features:

- Lowest electrical loss for reinforced PTFE material.
- Low moisture absorption.
- Isotropic
- Uniform electrical properties over frequency.
- Excellent chemical resistance.

Some Typical Applications:

- Commercial Airline Telephones
- Microstrip and Stripline Circuits
- Millimeter Wave Applications
- Military Radar Systems
- Missile Guidance Systems
- Point to Point Digital Radio Antennas



RT/duroid® 5870 and 5880 glass microfiber reinforced PTFE composites are designed for exacting stripline and microstrip circuit applications.

Glass reinforcing microfibers are randomly oriented to maximize benefits of fiber reinforcement in the directions most valuable to circuit producers and in the final circuit application.

The dielectric constant of RT/duroid 5870 and 5880 laminates is uniform from panel to panel and is constant over a wide frequency range. Its low dissipation factor extends the usefulness of RT/duroid 5870 and 5880 to Ku-band and above.

RT/duroid 5870 and 5880 laminates are easily cut, sheared and machined to shape. They are resistant to all solvents and reagents, hot or cold, normally used in etching printed circuits or in plating edges and holes.

Normally supplied as a laminate with electrodeposited copper of ¼ to 2 ounces/ft.^{2} (8 to 70μm) on both sides, RT/duroid 5870 and 5880 composites can also be clad with rolled copper foil for more critical electrical applications. Cladding with aluminum, copper or brass plate may also be specified.

When ordering RT/duroid 5870 and 5880 laminates, it is important to specify dielectric thickness, tolerance, rolled or electrodeposited copper foil, and weight of copper foil required.

PROPERTY	TYPICAL VALUE				DIRECTION	UNITS	CONDITION	TEST METHOD
	RT/duroid® 5870		RT/duroid 5880					
Dielectric Constant, ε_r	2.33 2.33 ± 0.02 spec.		2.20 2.20 ± 0.02 spec.		Z Z		C24/23/50 C24/23/50	1 MHz IPC-TM-650, 2.5.5.3 10 GHz IPC-TM-2.5.5.5
Dissipation Factor, tan δ	0.0005 0.0012		0.0004 0.0009		Z Z		C24/23/50 C24/23/50	1 MHz IPC-TM-650, 2.5.5.3 10 GHz IPC-TM-2.5.5.5
Thermal Coefficient of ε_r	-115		-125			ppm/°C	-50 - 150°C	IPC-TM-650, 2.5.5.5
Volume Resistivity	2 X 10^7		2 X 10^7		Z	Mohm cm	C96/35/90	ASTM D257
Surface Resistivity	2 X 10^8		3 X 10^7		Z	Mohm	C/96/35/90	ASTM D257
	Test at 23°C	Test at 100°C	Test at 23°C	Test at 100°C				
Tensile Modulus	1300 (189)	490 (71)	1070 (156)	450 (65)	X	MPa (kpsi)	A	ASTM D638
	1280 (185	430 (63)	860 (125)	380 (55)	Y			
ultimate stress	50 (7.3)	34 (4.8)	29 (4.2)	20 (2.9)	X			
	42 (6.1)	34 (4.8)	27 (3.9)	18 (2.6)	Y			
ultimate strain	9.8	8.7	6.0	7.2	X	%		
	9.8	8.6	4.9	5.8	Y			
Compressive Modulus	1210 (176)	680 (99)	710 (103)	500 (73)	X	MPa (kpsi)	A	ASTM D695
	1360 (198)	860 (125)	710 (103)	500 (73)	Y			
	803 (120)	520 (76)	940 (136)	670 (97)	Z			
ultimate stress	30 (4.4)	23 (3.4)	27 (3.9)	22 (3.2)	X			
	37 (5.3)	25 (3.7)	29 (5.3)	21 (3.1)	Y			
	54 (7.8)	37 (5.3)	52 (7.5)	43 (6.3)	Z			
ultimate strain	4.0	4.3	8.5	8.4	X	%		
	3.3	3.3	7.7	7.8	Y			
	8.7	8.5	12.5	17.6	Z			
Deformation Under Load, Test at 150°C			1.0		Z	%	24hr/14 MPa (2 Kpsi)	ASTM D621
Heat Distortion Temperature	>260 (>500)		>260 (>500)		X,Y	°C (°F)	1.82 MPa (264 psi)	ASTM D648
Specific Heat	0.96 (0.23)		0.96 (0.23)			J/g/K (cal/g/C)		Calculated
Moisture Absorption Thickness 0.31" (0.8mm)	0.9 (0.02)		0.9 (0.02)			mg (%)	D24/23	ASTM D570
0.62" (1.6mm)	13 (0.015)		13 (0.015					
Thermal Conductivity	0.22		0.20		Z	W/m/K		ASTM C518
	X	Y	Z	X	Y	Z			
Thermal Expansion	-5.0	-5.5	-11.6	-6.1	-8.7	-18.7	-100°C	ASTM D3386 (10K/min) (Values given are total change from a base temperature of 35°C)
	-0.6	-0.9	-4.0	-0.9	-1.8	-6.9	15	
	-0.3	-0.4	-2.6	-0.5	-0.9	-4.5	25	
	0.7	0.9	7.5	1.1	1.5	8.7	75	
	1.8	2.2	22.0	2.3	3.2	28.3	150	
	3.4	4.0	58.9	3.8	5.5	69.5	250	
Td	500		500			°C TGA		ASTM D3850
Density	2.2		2.2					ASTM D792
Copper Peel	20.8 (3.7)		22.8 (4.0)			pli (N/mm)	after solder float	IPC-TM-650 2.4.8
Flammability	94V-0		94V-0					UL
Lead-Free Process Compatible	Yes		Yes					

[1] SI unit given first with other frequently used units in parentheses.
[2] References: Internal TR's 1430, 2224, 2854. Test were at 23°C unless otherwise noted.
Typical values should not be used for specification limits.

STANDARD THICKNESS:		STANDARD PANEL SIZE:	STANDARD COPPER CLADDING:
0.005" (0.127mm),	0.031" (0.787mm)	18" X 12" (457 X 305mm)	¼ oz. (8 μm) electrodeposited copper foil.
0.010" (0.254mm),	0.062" (1.575mm)	18" X 24" (457 X 610mm)	½ oz. (17μm), 1 oz. (35μm), 2 oz. (70μm) electrodeposited and rolled copper foil.
0.015" (0.381mm),	0.125" (3.175mm)	18" X 36" (457 X 915mm)	
0.020" (0.508mm),		18" X 48" (457 X 1.224m)	

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